

## Dual 1:2 Low Additive Jitter LVDS Buffer

Check for Samples: [CDCLVD2102](#)

### FEATURES

- Dual 1:2 Differential Buffer
- Low Additive Jitter <300 fs RMS in 10-kHz to 20-MHz
- Low Within Bank Output Skew of 15 ps (Max)
- Universal Inputs Accept LVDS, LVPECL, LVCMOS
- One Input Dedicated for Two Outputs
- Total of 4 LVDS Outputs, ANSI EIA/TIA-644A Standard Compatible
- Clock Frequency up to 800 MHz
- 2.375–2.625V Device Power Supply
- LVDS Reference Voltage,  $V_{AC\_REF}$ , Available for Capacitive Coupled Inputs
- Industrial Temperature Range –40°C to 85°C
- Packaged in 3mm × 3mm 16-Pin QFN (RGT)
- ESD Protection Exceeds 3 kV HBM, 1 kV CDM

### APPLICATIONS

- Telecommunications/Networking
- Medical Imaging
- Test and Measurement Equipment
- Wireless Communications
- General Purpose Clocking

### DESCRIPTION

The CDCLVD2102 clock buffer distributes two clock inputs (IN0, IN1) to a total of 4 pairs of differential LVDS clock outputs (OUT0, OUT3). Each buffer block consists of one input and 2 LVDS outputs. The inputs can either be LVDS, LVPECL, or LVCMOS.

The CDCLVD2102 is specifically designed for driving 50-Ω transmission lines. If driving the inputs in single ended mode, the appropriate bias voltage ( $V_{AC\_REF}$ ) should be applied to the unused negative input pin.

Using the control pin (EN), outputs can be either disabled or enabled. If the EN pin is left open two buffers with all outputs are enabled, if switched to a logical "0" both buffers with all outputs are disabled (static logical "0"), if switched to a logical "1", one buffer with two outputs is disabled and another buffer with two outputs is enabled. The part supports a fail safe function. It incorporates an input hysteresis, which prevents random oscillation of the outputs in absence of an input signal.

The device operates in 2.5V supply environment and is characterized from –40°C to 85°C (ambient temperature). The CDCLVD2102 is packaged in small 16-pin, 3-mm × 3-mm QFN package.

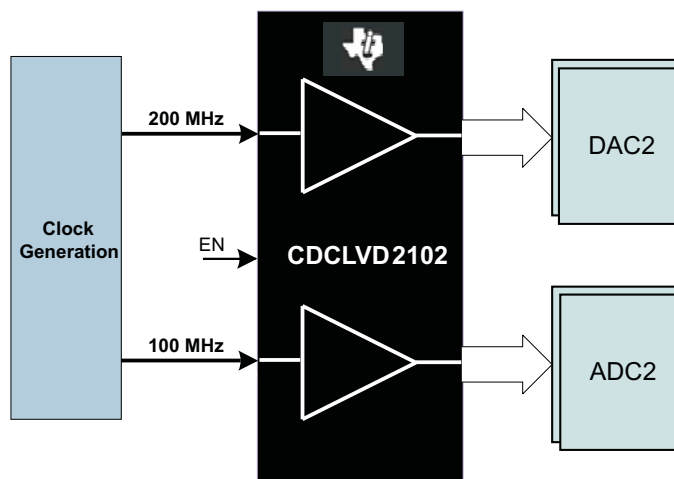


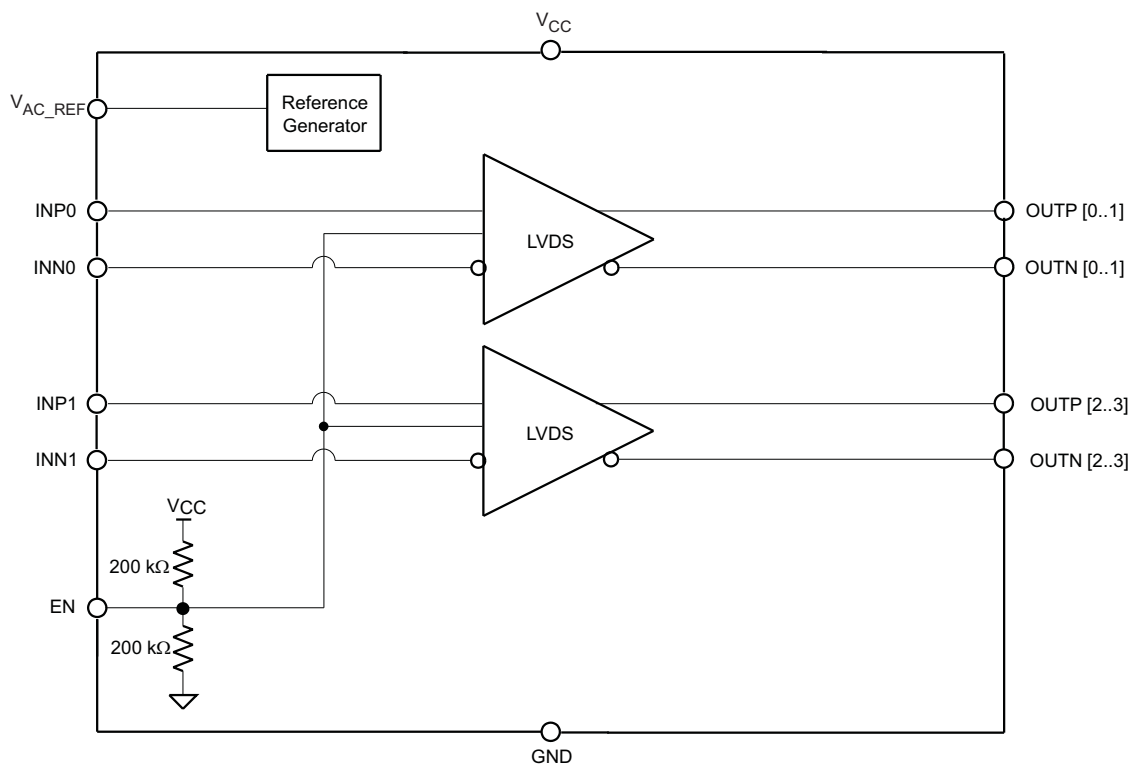
Figure 1. Application Example



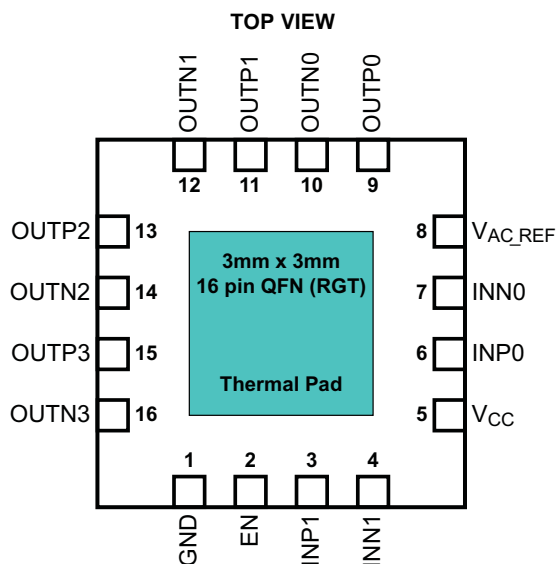
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



**Figure 2. CDCLVD2102 Block Diagram**



## PIN FUNCTIONS

PIN		TYPE	DESCRIPTION	
NAME	NO.			
VCC	5	Power	2.5V supplies for the device	
GND	1	Ground	Device ground	
INP0, INN0	6, 7	Input	Differential input pair or single ended input	
INP1, INN1	3, 4	Input	Differential redundant input pair or single ended input	
V <sub>AC_REF</sub>	8	Output	Bias voltage output for capacitive coupled inputs. If used, it is recommended to use a 0.1µF to GND on this pin	
OUTP0, OUTN0	9, 10	Output	Differential LVDS output pair no. 0	INP0/INN0 is the input
OUTP1, OUTN1	11, 12	Output	Differential LVDS output pair no. 1	
OUTP2, OUTN2	13, 14	Output	Differential LVDS output pair no. 2	INP1/INN1 is the input
OUTP3, OUTN3	15, 16	Output	Differential LVDS output pair no. 3	
EN	2	Input with internal 200kΩ pull-up and pull-down	Control pin – enables or disables the outputs, (See <a href="#">Table 1</a> )	
Thermal Pad			See thermal management recommendations	

**Table 1. Output Control Table**

EN	CLOCK OUTPUTS
0	All outputs disabled (static "0")
OPEN	All outputs enabled
1	OUT0, OUT1 enabled and OUT2, OUT3 disabled (static "0")

## ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	VALUE / UNIT
Supply voltage range, V <sub>CC</sub>	–0.3 to 2.8 V
Input voltage, V <sub>I</sub>	–0.2 to (V <sub>CC</sub> + 0.2) V
Output voltage range, V <sub>O</sub>	–0.2 to (V <sub>CC</sub> + 0.2) V
Driver short circuit current, I <sub>OSD</sub>	See Note <sup>(2)</sup>
Electrostatic discharge (HBM, 1.5 kΩ, 100 pF)	>3000 V

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions” is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.

(2) The outputs can handle permanent short.

## RECOMMENDED OPERATING CONDITIONS

	MIN	TYP	MAX	UNITS
Device supply voltage, V <sub>CC</sub>	2.375	2.5	2.625	V
Ambient temperature, T <sub>A</sub>	–40		85	°C

**THERMAL INFORMATION**

THERMAL METRIC <sup>(1)</sup>		CDCLVD2102	UNITS
		RGT	
		16 PINS	
$\theta_{JA}$	Junction-to-ambient thermal resistance	51.3	°C/W
$\theta_{JC(top)}$	Junction-to-case(top) thermal resistance	85.4	
$\theta_{JB}$	Junction-to-board thermal resistance	20.1	
$\psi_{JT}$	Junction-to-top characterization parameter	1.3	
$\psi_{JB}$	Junction-to-board characterization parameter	19.4	
$\theta_{JC(bottom)}$	Junction-to-case(bottom) thermal resistance	6	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

**ELECTRICAL CHARACTERISTICS:**

At  $V_{CC} = 2.375\text{ V}$  to  $2.625\text{ V}$  and  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$  (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
EN PIN INPUT CHARACTERISTICS						
Vd <sub>I3</sub>	3-State	Open	0.5×V <sub>CC</sub>			V
Vd <sub>IH</sub>	Input high voltage		0.7×V <sub>CC</sub>			V
Vd <sub>IL</sub>	Input low voltage		0.2×V <sub>CC</sub>			V
Id <sub>IH</sub>	Input high current	V <sub>CC</sub> = 2.625 V, V <sub>IH</sub> = 2.625 V	30			μA
Id <sub>IL</sub>	Input low current	V <sub>CC</sub> = 2.625 V, V <sub>IL</sub> = 0 V	–30			μA
R <sub>pull(EN)</sub>	Input pull-up/ pull-down resistor		200			kΩ
2.5V LVCMOS (see Figure 7) INPUT CHARACTERISTICS						
f <sub>IN</sub>	Input frequency		200			MHz
V <sub>th</sub>	Input threshold voltage	External threshold voltage applied to complementary input	1.1	1.5		V
V <sub>IH</sub>	Input high voltage		V <sub>th</sub> + 0.1	V <sub>CC</sub>		V
V <sub>IL</sub>	Input low voltage		0	V <sub>th</sub> – 0.1		V
I <sub>IH</sub>	Input high current	V <sub>CC</sub> = 2.625 V, V <sub>IH</sub> = 2.625 V	10			μA
I <sub>IL</sub>	Input low current	V <sub>CC</sub> = 2.625 V, V <sub>IL</sub> = 0 V	–10			μA
ΔV/ΔT	Input edge rate	20% – 80%	1.5			V/ns
C <sub>IN</sub>	Input capacitance		2.5			pF
DIFFERENTIAL INPUT CHARACTERISTICS						
f <sub>IN</sub>	Input frequency	Clock input	800			MHz
V <sub>IN, DIFF</sub>	Differential input voltage peak-to-peak	V <sub>ICM</sub> = 1.25 V	0.3	1.6		V <sub>P-P</sub>
V <sub>ICM</sub>	Input common-mode voltage range	V <sub>IN, DIFF, PP</sub> > 0.4V	1	V <sub>CC</sub> – 0.3		V
I <sub>IH</sub>	Input high current	V <sub>CC</sub> = 2.625 V, V <sub>IH</sub> = 2.625 V	10			μA
I <sub>IL</sub>	Input low current	V <sub>CC</sub> = 2.625 V, V <sub>IL</sub> = 0 V	–10			μA
ΔV/ΔT	Input edge rate	20% to 80%	0.75			V/ns
C <sub>IN</sub>	Input capacitance		2.5			pF

**ELECTRICAL CHARACTERISTICS: (continued)**

At  $V_{CC} = 2.375\text{ V}$  to  $2.625\text{ V}$  and  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$  (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>LVDS OUTPUT CHARACTERISTICS</b>						
$ V_{OD} $	Differential output voltage magnitude	$V_{IN, DIFF, PP} = 0.3\text{ V}, R_L = 100\ \Omega$	250		450	mV
$\Delta V_{OD}$	Change in differential output voltage magnitude		–15		15	mV
$V_{OC(SS)}$	Steady-state common mode output voltage		1.1		1.375	V
$\Delta V_{OC(SS)}$	Steady-state common mode output voltage	$V_{IN, DIFF, PP} = 0.6\text{ V}, R_L = 100\ \Omega$	–15		15	mV
$V_{ring}$	Output overshoot and undershoot	Percentage of output amplitude $V_{OD}$			10%	
$V_{OS}$	Output ac common mode	$V_{IN, DIFF, PP} = 0.6\text{ V}, R_L = 100\ \Omega$		25	70	mV <sub>PP</sub>
$I_{OS}$	Short-circuit output current	$V_{OD} = 0\text{ V}$			±24	mA
$t_{PD}$	Propagation delay	$V_{IN, DIFF, PP} = 0.3\text{ V}$		1.5	2.5	ns
$t_{SK, PP}$	Part-to-part skew				600	ps
$t_{SK, O\_WB}$	Within bank output skew				15	ps
$t_{SK, O\_BB}$	Bank-to-bank output skew	Both inputs are phase aligned			100	ps
$t_{SK, P}$	Pulse skew(with 50% duty cycle input)	Crossing-point-to-crossing-point distortion	–50		50	ps
$t_{RJIT}$	Random additive jitter (with 50% duty cycle input)	Edge speed = $0.75\text{ V/ns}$ , 10 kHz – 20 MHz			0.3	ps, RMS
$t_R/t_F$	Output rise/fall time	20% to 80%, $100\ \Omega$ , 5 pF	50		300	ps
$I_{CCSTAT}$	Static supply current	Outputs unterminated, $f = 0\text{ Hz}$		27	45	mA
$I_{CC100}$	Supply current	All outputs enabled, $R_L = 100\ \Omega$ , $f = 100\text{ MHz}$		49	77	mA
$I_{CC800}$	Supply current	All outputs enabled, $R_L = 100\ \Omega$ , $f = 800\text{ MHz}$		76	106	mA
<b><math>V_{AC\_REF}</math> CHARACTERISTICS</b>						
$V_{AC\_REF}$	Reference output voltage	$V_{CC} = 2.5\text{ V}$ , $I_{load} = 100\ \mu\text{A}$	1.1	1.25	1.35	V

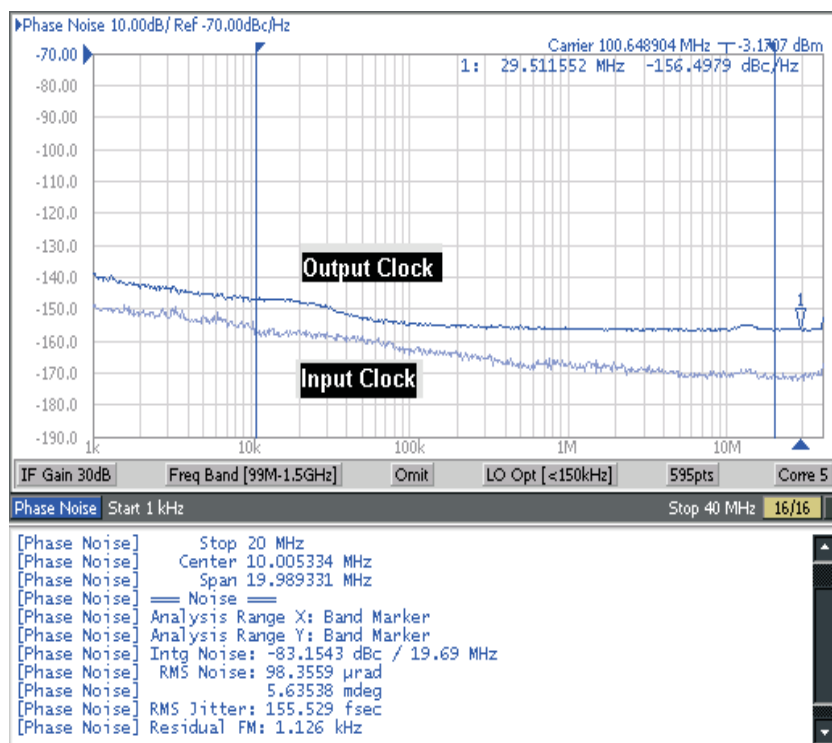
### Typical Additive Phase Noise Characteristics for 100 MHz Clock

PARAMETER		MIN	TYP	MAX	UNIT
phn <sub>100</sub>	Phase noise at 100 Hz offset		-132.9		dBc/Hz
phn <sub>1k</sub>	Phase noise at 1 kHz offset		-138.8		dBc/Hz
phn <sub>10k</sub>	Phase noise at 10 kHz offset		-147.4		dBc/Hz
phn <sub>100k</sub>	Phase noise at 100 kHz offset		-153.6		dBc/Hz
phn <sub>1M</sub>	Phase noise at 1 MHz offset		-155.2		dBc/Hz
phn <sub>10M</sub>	Phase noise at 10 MHz offset		-156.2		dBc/Hz
phn <sub>20M</sub>	Phase noise at 20 MHz offset		-156.6		dBc/Hz
t <sub>RJIT</sub>	Random additive jitter from 10 kHz to 20 MHz		171		fs, RMS

### Typical Additive Phase Noise Characteristics for 737.27 MHz Clock

PARAMETER		MIN	TYP	MAX	UNIT
phn <sub>100</sub>	Phase noise at 100 Hz offset		-80.2		dBc/Hz
phn <sub>1k</sub>	Phase noise at 1 kHz offset		-114.3		dBc/Hz
phn <sub>10k</sub>	Phase noise at 10 kHz offset		-138		dBc/Hz
phn <sub>100k</sub>	Phase noise at 100 kHz offset		-143.9		dBc/Hz
phn <sub>1M</sub>	Phase noise at 1 MHz offset		-145.2		dBc/Hz
phn <sub>10M</sub>	Phase noise at 10 MHz offset		-146.5		dBc/Hz
phn <sub>20M</sub>	Phase noise at 20 MHz offset		-146.6		dBc/Hz
t <sub>RJIT</sub>	Random additive jitter from 10 kHz to 20 MHz		65		fs, RMS

# **TYPICAL CHARACTERISTICS** **INPUT CLOCK AND OUTPUT CLOCK PHASE NOISES** **vs** **FREQUENCY FROM THE CARRIER ( $T_A = 25^\circ\text{C}$ and $V_{CC} = 2.5\text{V}$ )**



Input clock jitter is 32 fs from 10 kHz to 20 MHz and additive RMS jitter is 152 fs

Figure 3. 100 MHz Input and Output Phase Noise Plot

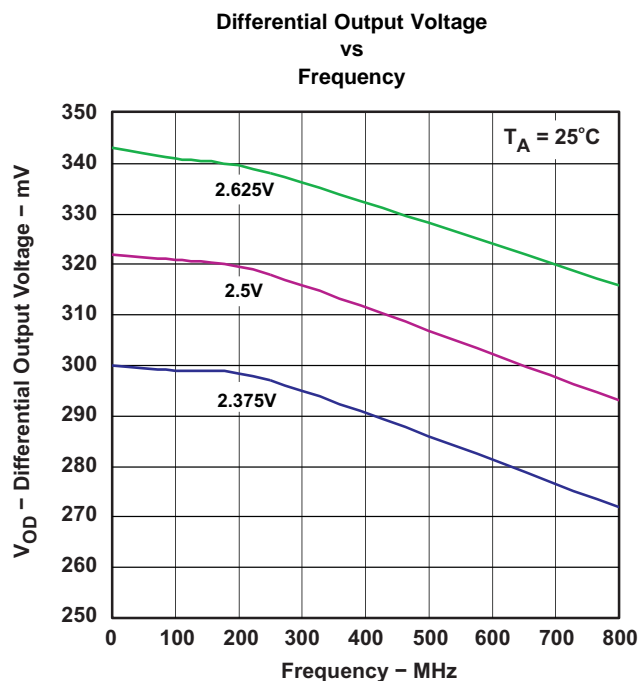


Figure 4.

## TEST CONFIGURATIONS

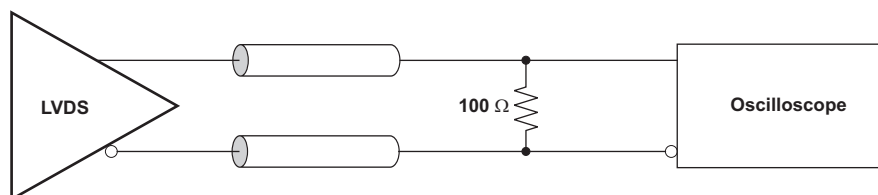


Figure 5. LVDS Output DC Configuration During Device Test

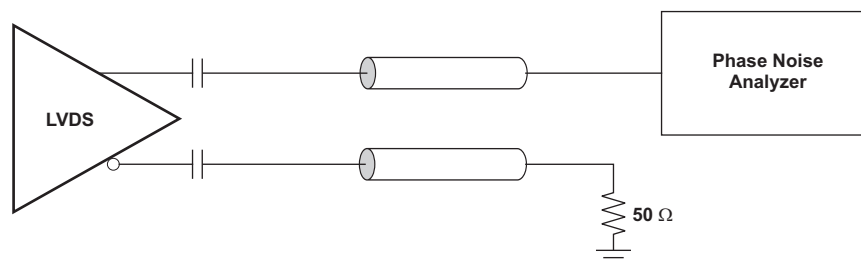


Figure 6. LVDS Output AC Configuration During Device Test

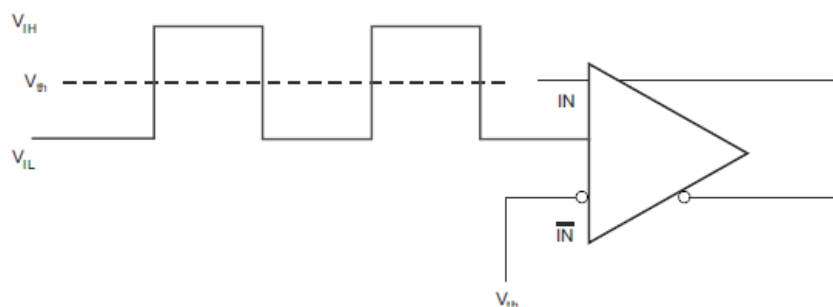


Figure 7. DC Coupled LVCMOS Input During Device Test

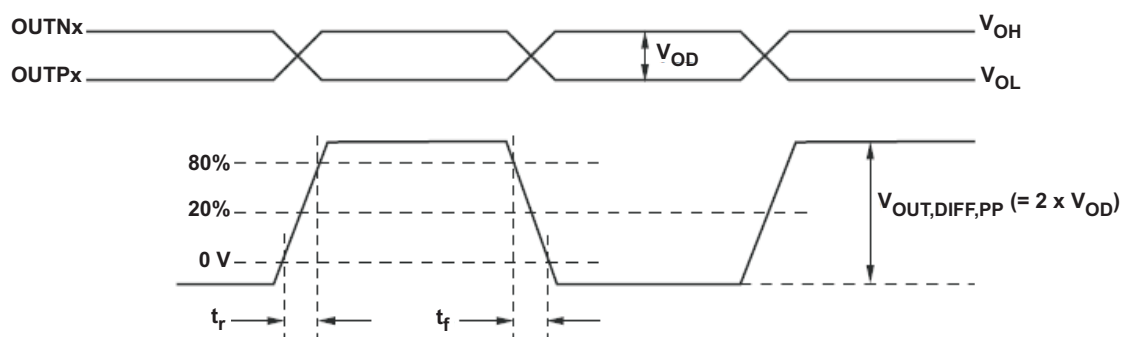
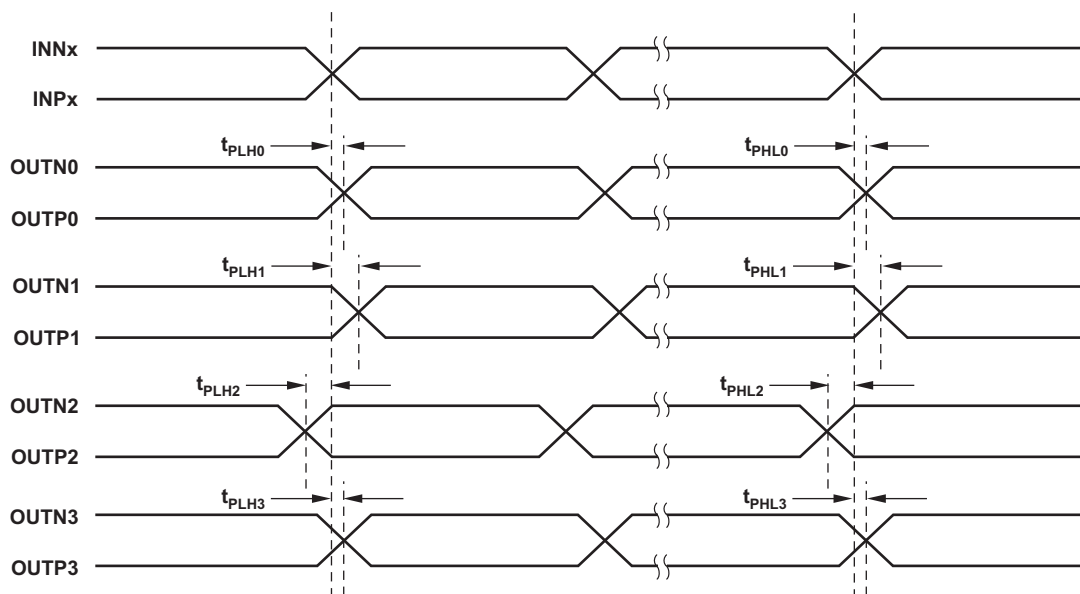


Figure 8. Output Voltage and Rise/Fall Time





- Output skew is calculated as the greater of the following: As the difference between the fastest and the slowest  $t_{PLHn}$  or the difference between the fastest and the slowest  $t_{PHLn}$  ( $n = 0, 1, 2, 3$ ).
- Part-to-part skew is calculated as the greater of the following: As the difference between the fastest and the slowest  $t_{PLHn}$  or the difference between the fastest and the slowest  $t_{PHLn}$  across multiple devices ( $n = 0, 1, 2, 3$ ).
- Both inputs ( $IN0$  and  $IN1$ ) are phase aligned.

Figure 9. Output Skew and Part-to-Part Skew

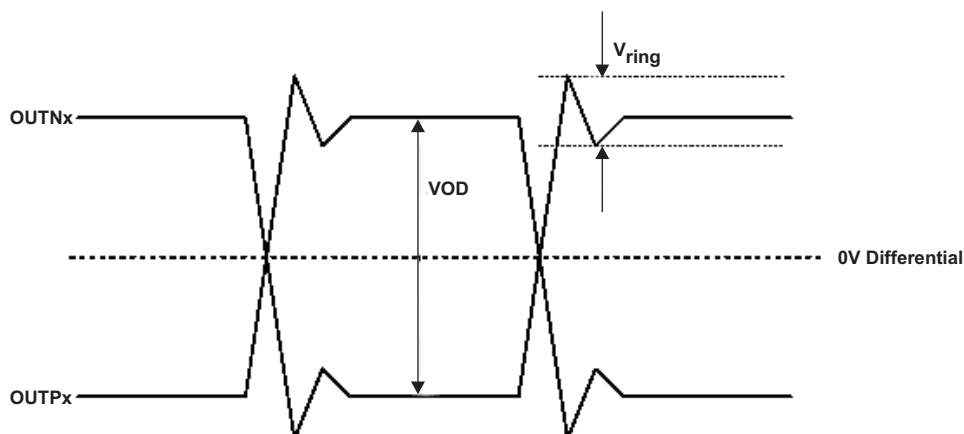


Figure 10. Output Overshoot and Undershoot

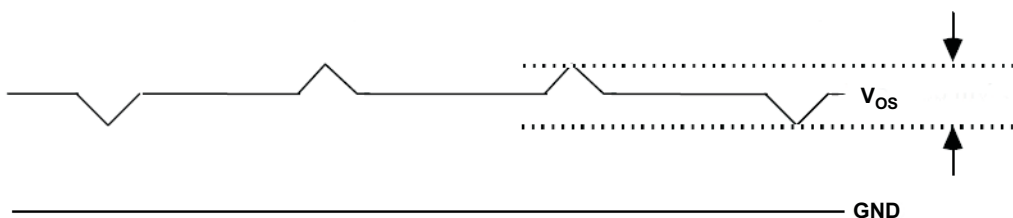


Figure 11. Output AC Common Mode

## APPLICATION INFORMATION

### THERMAL MANAGEMENT

For reliability and performance reasons, the die temperature should be limited to a maximum of 125°C.

The device package has an exposed pad that provides the primary heat removal path to the printed circuit board (PCB). To maximize the heat dissipation from the package, a thermal landing pattern including multiple vias to a ground plane must be incorporated into the PCB within the footprint of the package. The Thermal Pad must be soldered down to ensure adequate heat conduction to of the package. Figure 12 shows a recommended land and via pattern.

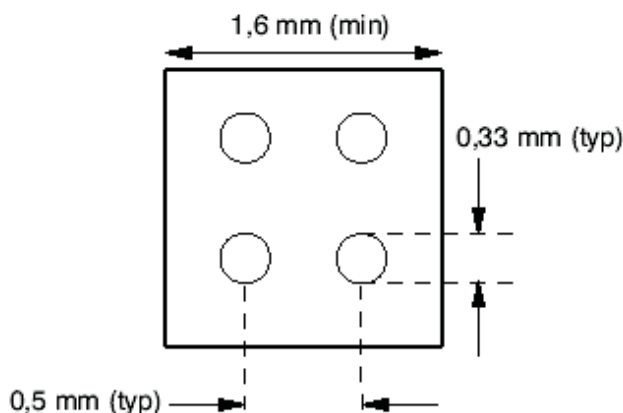


Figure 12. Recommended PCB Layout

### POWER-SUPPLY FILTERING

High-performance clock buffers are sensitive to noise on the power supply, which can dramatically increase the additive jitter of the buffer. Thus, it is essential to reduce noise from the system power supply, especially when jitter/phase noise is critical to applications.

Filter capacitors are used to eliminate the low-frequency noise from the power supply, where the bypass capacitors provide the very low impedance path for high-frequency noise and guard the power-supply system against the induced fluctuations. These bypass capacitors also provide instantaneous current surges as required by the device and should have low equivalent series resistance (ESR). To properly use the bypass capacitors, they must be placed very close to the power-supply pins and laid out with short loops to minimize inductance. It is recommended to add as many high-frequency (for example, 0.1  $\mu\text{F}$ ) bypass capacitors as there are supply pins in the package. It is recommended, but not required, to insert a ferrite bead between the board power supply and the chip power supply that isolates the high-frequency switching noises generated by the clock driver; these beads prevent the switching noise from leaking into the board supply. Choose an appropriate ferrite bead with very low dc resistance because it is imperative to provide adequate isolation between the board supply and the chip supply, as well as to maintain a voltage at the supply pins that is greater than the minimum voltage required for proper operation.

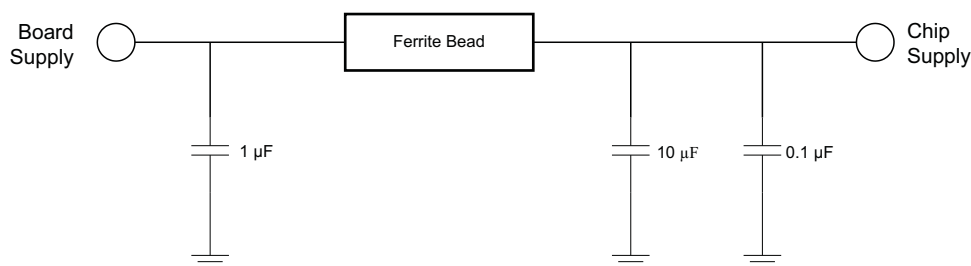


Figure 13. Power-Supply Decoupling

## LVDS OUTPUT TERMINATION

The proper LVDS termination for signal integrity over two  $50\ \Omega$  lines is  $100\ \Omega$  between the outputs on the receiver end. Either dc-coupled termination or ac-coupled termination can be used for LVDS outputs. It is recommended to place termination resistor close to the receiver. If the receiver is internally biased to a voltage different than the output common mode voltage of the CDCLVD2102, ac-coupling should be used. If the LVDS receiver has internal  $100\ \Omega$  termination, external termination must be omitted.

Unused outputs can be left open without connecting any trace to the output pins.

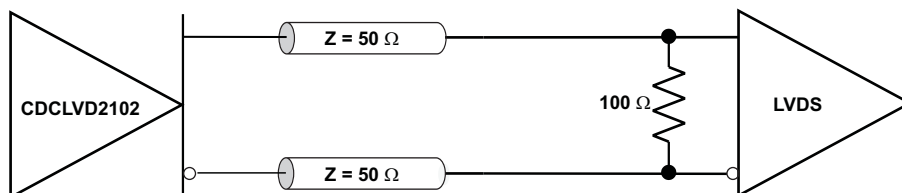


Figure 14. Output DC Termination

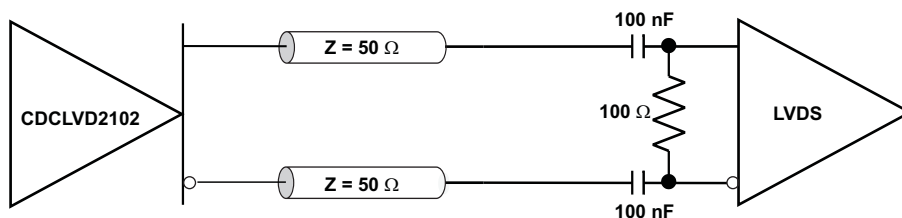


Figure 15. Output AC Termination With Receiver Internally Biased

## INPUT TERMINATION

The CDCLVD2102 inputs can be interfaced with LVDS, LVPECL, or LVCMOS drivers.

LVDS Driver can be connected to CDCLVD2102 inputs with dc or ac coupling as shown [Figure 16](#) and [Figure 17](#), respectively.

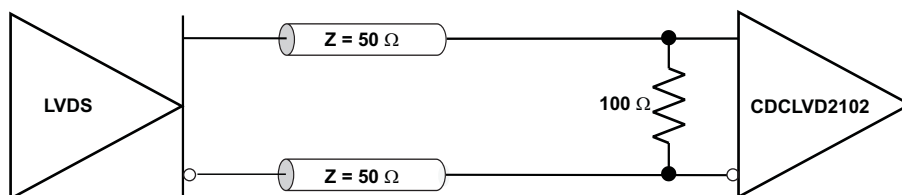


Figure 16. LVDS Clock Driver Connected to CDCLVD2102 Input (DC Coupled)

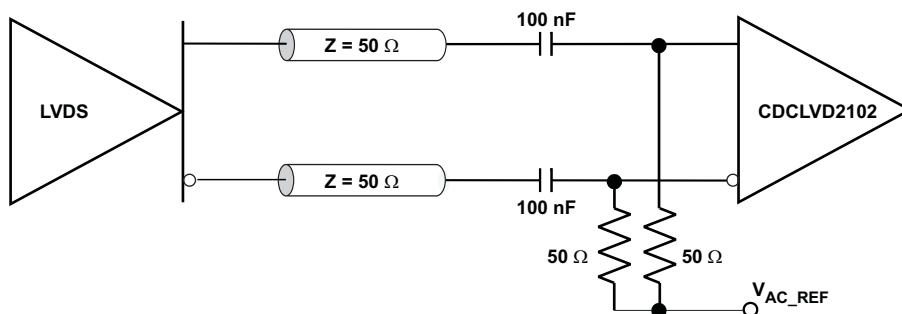
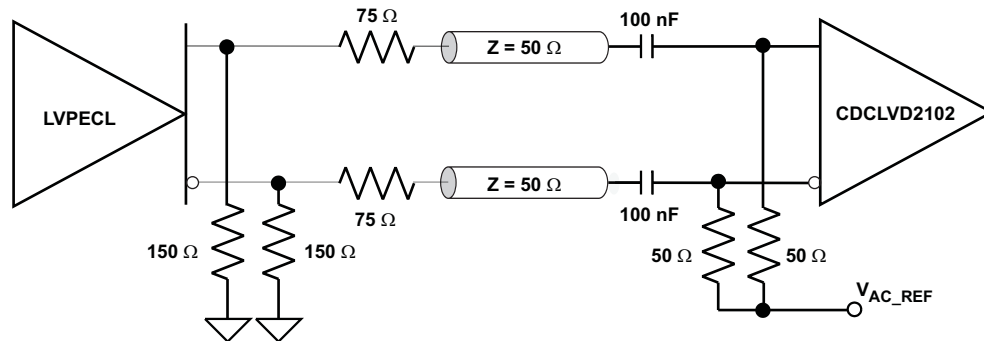


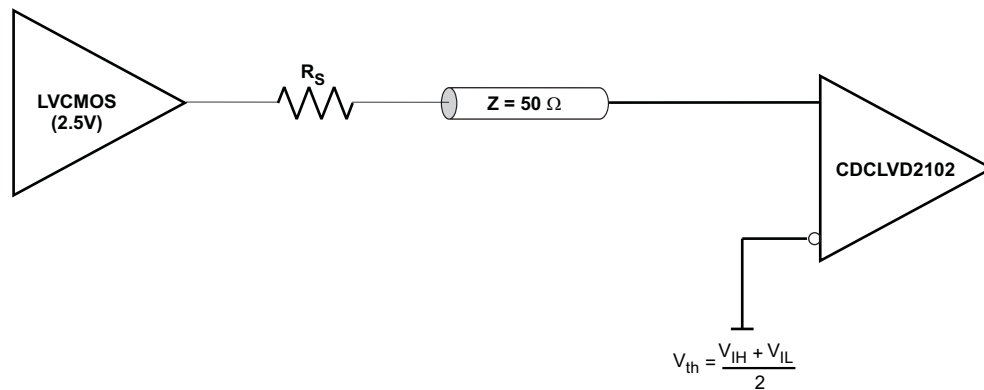
Figure 17. LVDS Clock Driver Connected to CDCLVD2102 Input (AC Coupled)

Figure 18 shows how to connect LVPECL inputs to the CDCLVD2102. The series resistors are required to reduce the LVPECL signal swing if the signal swing is  $>1.6 V_{PP}$ .



**Figure 18. LVPECL Clock Driver Connected to CDCLVD2102 Input**

Figure 19 illustrates how to couple a 2.5 V LVCMOS clock input to the CDCLVD2102 directly. The series resistance ( $R_S$ ) should be placed close to the LVCMOS driver if needed. 3.3 V LVCMOS clock input swing needs to be limited to  $V_{IH} \leq V_{CC}$ .



**Figure 19. 2.5V LVCMOS Clock Driver Connected to CDCLVD2102 Input**

If one of the buffers is used, then the other unused buffer should be disabled through the EN pin, and the unused input pins should be grounded by 1k $\Omega$  resistors.

## REVISION HISTORY

Changes from Original (May 2010) to Revision A	Page
• Changed Features bullet From: ESD Protection Exceeds 2kV HBM, 500V CDM To: ESD Protection Exceeds 3 kV HBM, 1 kV CDM .....	1
• Electrostatic discharge was <2000 .....	3
• $\Delta V_{OD}$ values, MIN was -50, MAX was 50 .....	5
• $V_{OC(SS)}$ MIN value was 1.125 .....	5
• $\Delta V_{OC(SS)}$ values, MIN was -50, MAX was 50 .....	5
• $V_{ring}$ MAX value was 20% .....	5
• $V_{OS}$ values, TYP was 30, MAX was 100 .....	5
• $t_{PD}$ MAX value was 2 .....	5
• $t_{SK, PP}$ - deleted the TYP value of 300 .....	5
• $t_R/t_F$ MIN value was 200 .....	5
• $I_{CCSTAT}$ MAX value was 42 .....	5
• Added new paragraph following <a href="#">Figure 19</a> .....	12

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">CDCLVD2102RGTR</a>	Active	Production	VQFN (RGT)   16	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	D2102
CDCLVD2102RGTR.A	Active	Production	VQFN (RGT)   16	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	D2102
<a href="#">CDCLVD2102RGTT</a>	Active	Production	VQFN (RGT)   16	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	D2102
CDCLVD2102RGTT.A	Active	Production	VQFN (RGT)   16	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	D2102
CDCLVD2102RGTTG4.A	Active	Production	VQFN (RGT)   16	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	D2102

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCLVD2102RGTR	VQFN	RGT	16	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCLVD2102RGTR	VQFN	RGT	16	3000	350.0	350.0	43.0



## TRAY



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (μm)	P1 (mm)	CL (mm)	CW (mm)
CDCLVD2102RGTR	RGT	VQFN	16	3000	35 X 14	150	315	135.9	7620	8.8	7.9	8.15
CDCLVD2102RGTR.A	RGT	VQFN	16	3000	35 X 14	150	315	135.9	7620	8.8	7.9	8.15
CDCLVD2102RGTT	RGT	VQFN	16	250	35 X 14	150	315	135.9	7620	8.8	7.9	8.15
CDCLVD2102RGTT.A	RGT	VQFN	16	250	35 X 14	150	315	135.9	7620	8.8	7.9	8.15

**RGT 16**

**GENERIC PACKAGE VIEW**

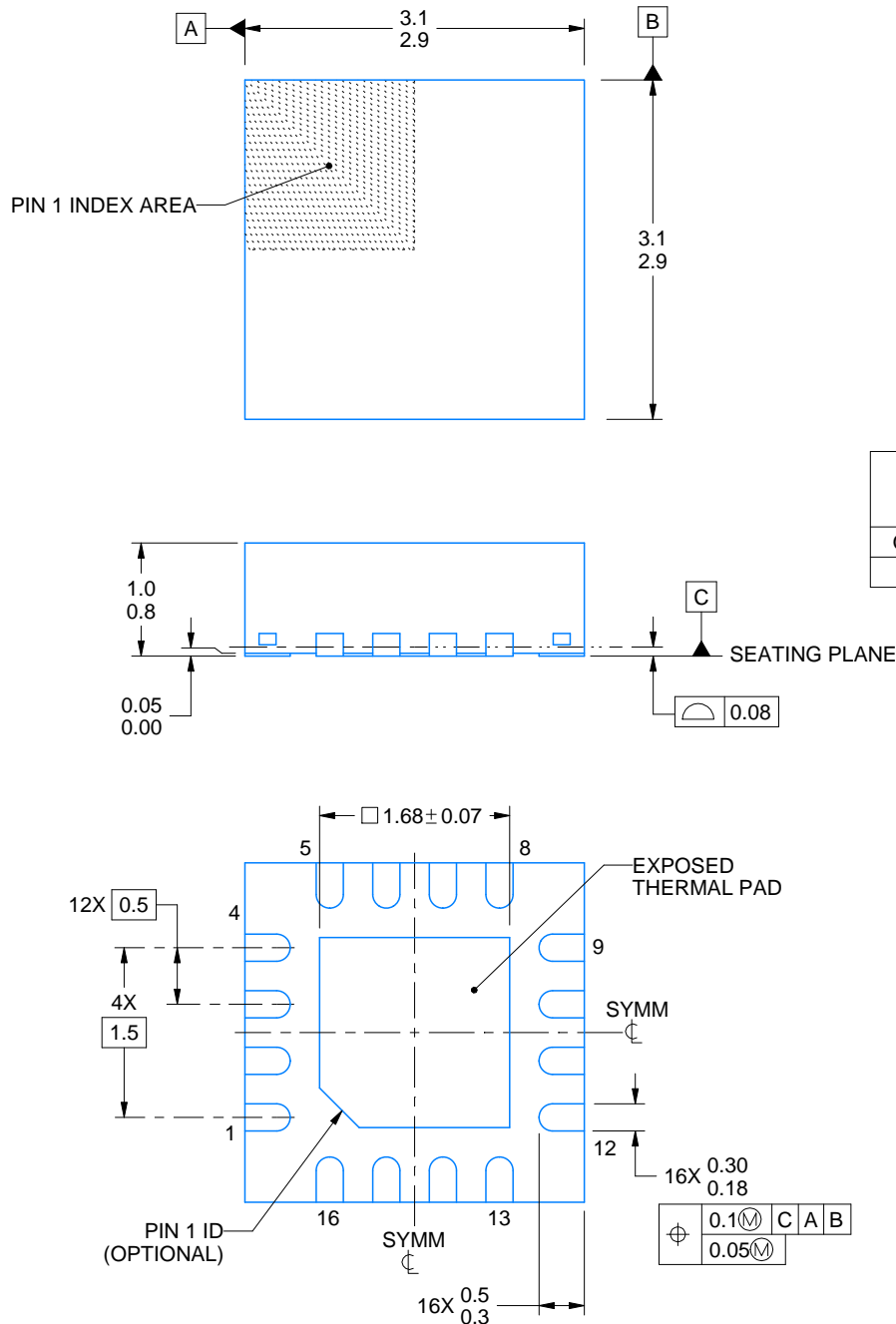
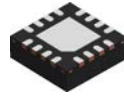
**VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

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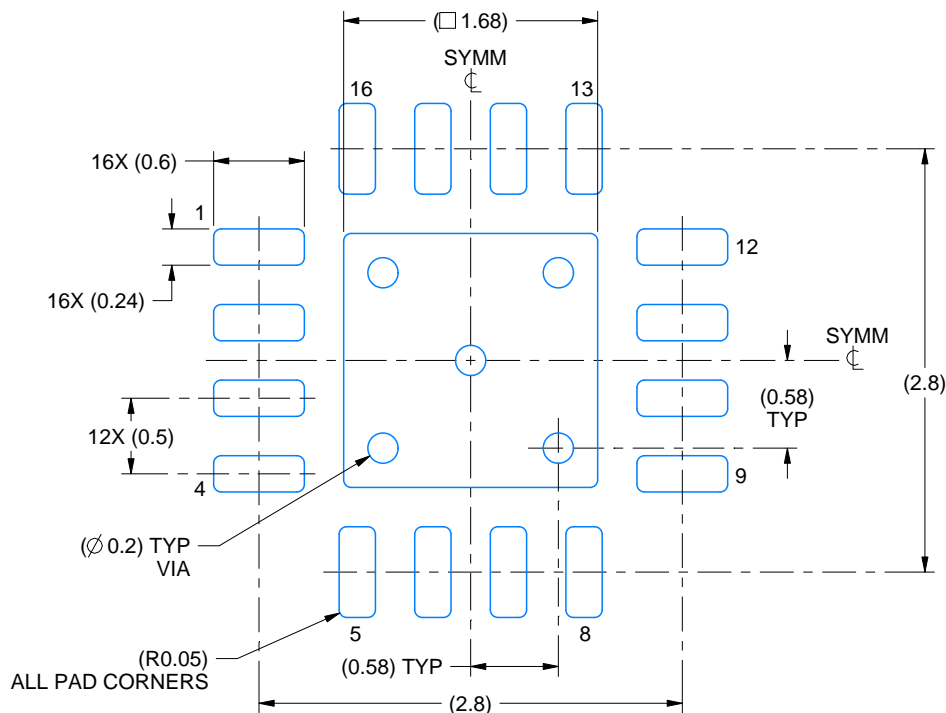
## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

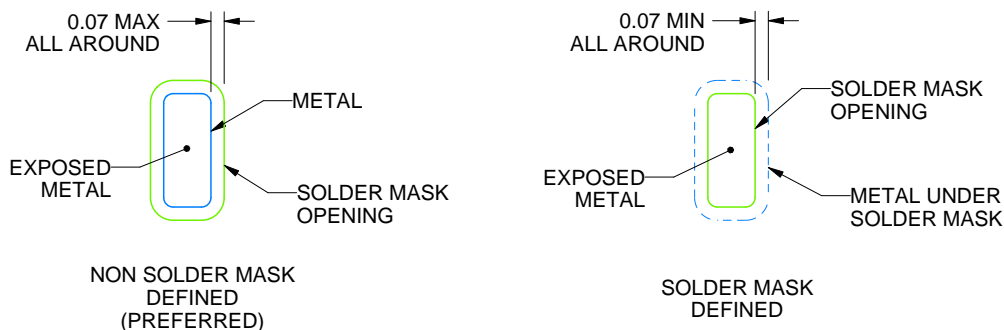
**RGT0016C**

## VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:20X



## SOLDER MASK DETAILS

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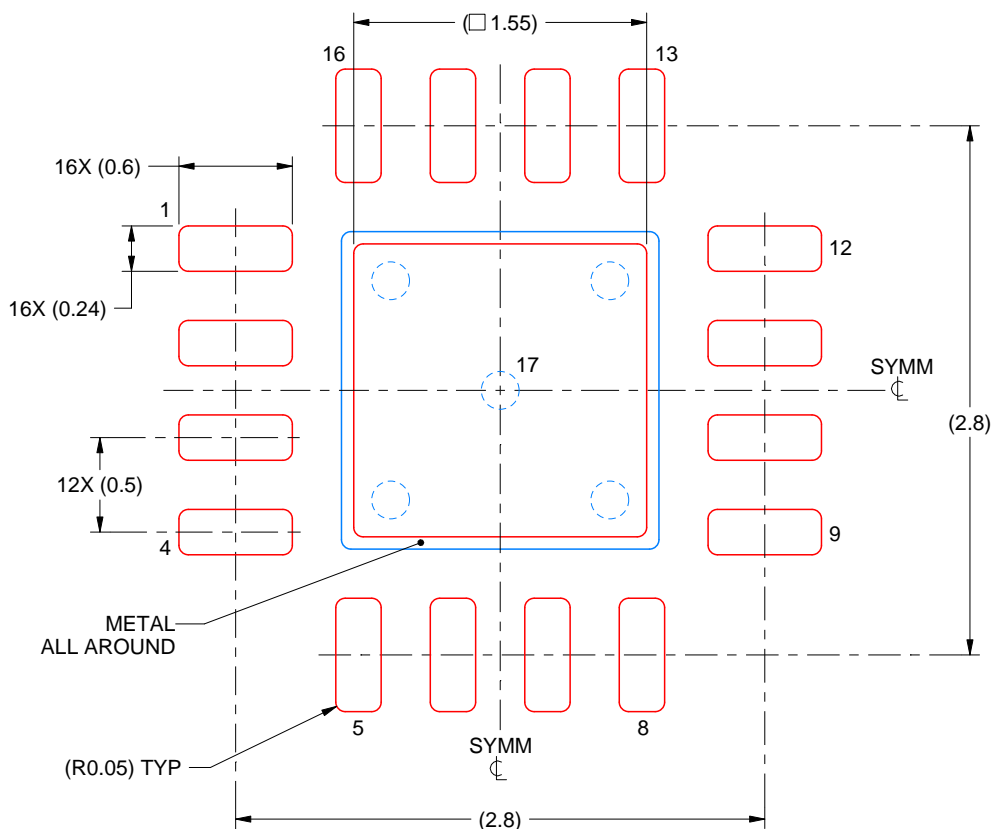
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

**RG T0016C**

### VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



## SOLDER PASTE EXAMPLE BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 17:  
85% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:25X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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